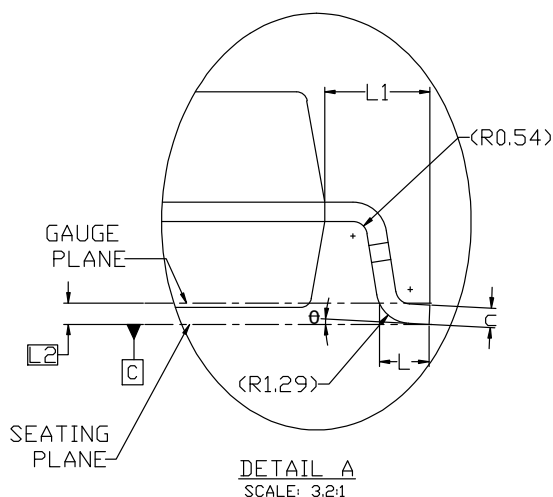
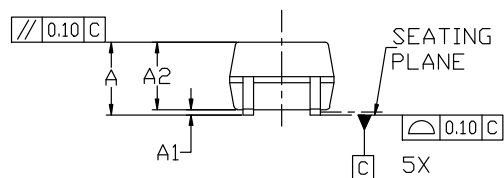
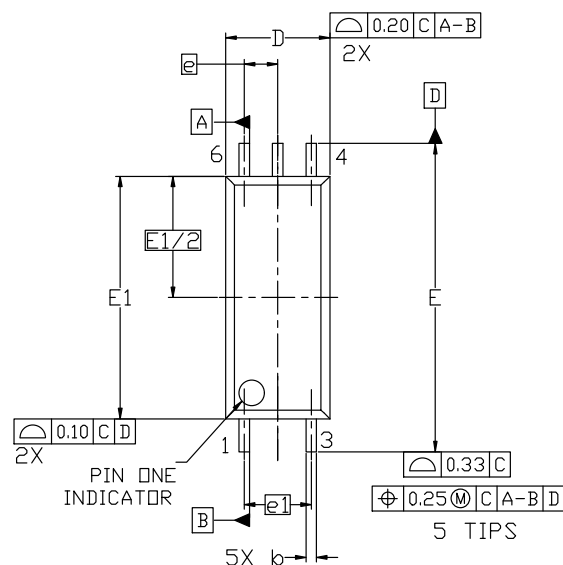


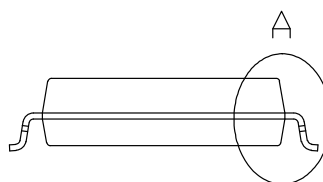
SOIC5 (6) 3.95x9.20x2.55, 1.27P
CASE 752AF
ISSUE B

DATE 24 JUL 2023

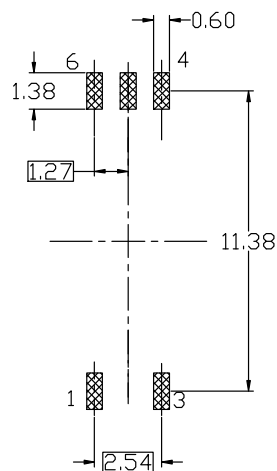


NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE DOES NOT
CONFORM TO ANY STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS,
MOLD FLASH AND TIE BAR PROTRUSIONS.
- D) DRAWING CONFORMS TO ASME Y14.5M-1994.



DIM	MILLIMETER		
	MIN.	NOM.	MAX.
A	--	--	2.95
A1	0.10	0.20	0.30
A2	2.45	2.55	2.65
b	0.31	0.41	0.51
c	0.19	0.22	0.25
D	3.85	3.95	4.05
E	11.60	11.70	11.80
E1	9.10	9.20	9.30
E1/2	4.60 BSC		
e	1.27 BSC		
e1	2.54 BSC		
L	0.44	0.59	0.74
L1	1.15	1.25	1.35
L2	0.25 BSC		
θ	0°	--	8°

LAND PATTERN
RECOMMENDATION

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DETAILS, PLEASE DOWNLOAD THE ON
SEMICONDUCTOR SOLDERING AND MOUNTING
TECHNIQUES REFERENCE MANUAL,
SOLDSRM/D.

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DESCRIPTION:	SOIC5 (6) 3.95x9.20x2.55, 1.27P	PAGE 1 OF 1

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